



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Tak Kin Chu et al.

Serial No.: 09/853,925

: Group Art Unit: 2813

Filed: May 9, 2001

: Examiner: Keilin, Erik J.

For: ELECTRONIC DEVICES WITH
DIFFUSION BARRIER
AND PROCESS FOR
MAKING SAME

: Attorney Docket No.: 83175

INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. §1.97((c)(1))

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 C.F.R. §1.56 and 1.97(c)(1), Applicants bring to the attention of the Examiner the documents listed on the attached Substitute Form PTO 1449 (in duplicate). A payment in the amount of \$180.00 is enclosed herewith for the filing of this Information Disclosure Statement.

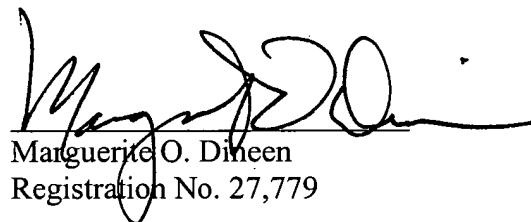
Applicant respectfully requests that the Examiner consider the listed documents and indicate that they were considered by making appropriate notations on the attached Substitute PTO 1449 form.

This submission does not represent that a search has been made or that no better art exists and does not constitute an admission that each or all of the listed documents are material or constitute "prior art". If the Examiner applies any of the documents as prior art against any claims in the application and Applicant determined that the cited documents do not constitute "prior art" under United States law, Applicant reserves the

right to present to the Patent Office the relevant facts and law regarding the appropriate status of such documents. Applicant further reserves the right to take appropriate action to establish the patentability of the disclosed invention over the listed documents, should one or more of the documents be applied against the claims of the present application.

Respectfully submitted,

Date: 5/17/04



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Examiner Initial	Item No.	Document No.	Date	Name	Class	Subclass
	1US	3,642,526	Feb-72	Itoh, et al.		
	2US	3,784,402	Jan-74	Reedy, Jr.		
	3US	4,368,098	Jan-83	Manasevit		
	4US	4,765,845	Aug-88	Takada, et al.		
	5US	4,983,535	Jan-91	Blanchard		
	6US	4,996,584	Feb-91	Young, et al.		
	7US	5,036,017	Jul-91	Noda		
	8US	5,084,417	Jan-92	Joshi, et al.		
	9US	5,135,808	Aug-92	Kimock, et al.		
	10US	5,221,853	Jun-93	Joshi, et al.		
	11US	5,225,561	Jul-93	Kirlin et al.		
	12US	5,232,872	Aug-93	Ohba		
	13US	5,280,012	Jan-94	Kirlin et al.		
	14US	5,352,917	Oct-94	Ohmi		
	15US	5,400,739	Mar-95	Kao et al.		
	16US	5,453,494	Sep-95	Kirlin et al.		
	17US	5,625,204	Apr-97	Kao et al.		
	18US	5,920,080	Jul-99	Jones		
	19US	5,932,006	Aug-99	Santiago et al.		
	20US	5,955,785	Sep-99	Gardner et al.		
	21US	5,965,810	Oct-99	Holbrook		
	22US	5,968,847	Oct-99	Ye et al.		
	23US	6,077,775	Jun-00	Stumborg et al.		
	24US	6,120,844	Sep-00	Chen et al.		
	25US	6,139,905	Oct-00	Chen et al.		
	26US	6,144,050	Nov-00	Stumborg et al.		
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DATE CONSIDERED:



Examiner Initial	Item No.	Foreign Patent Document No.	Date	Country	Translation (Yes/No)
	1F	WO 00/11731	3/1/2000	PCT	
	2F	JP 402143531-A	6/1/1990	Japan	
	3F	JP 6-164004	6/10/1994	Japan	
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DATE CONSIDERED:

MAY 20 2004

U.S. PATENT & TRADEMARK OFFICE

FORM PTO-1449 Modified

List of Patents and Publications Considered by Applicant

U.S. Patent Trademark Office

Page 1 (Other Documents)

U.S. App. No.: 09/853,925

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Group: 2813

Applicant: Chu et al

Docket No.: NSWC-1008US

Examiner Initial	Item No.	Other Documents (Including Author, Title, Date, Location and Pertinent Pages)
	1OD	Vogt et al., "Dielectric Barriers for Cu Metallization Systems", <u>Materials for Advanced Metallization</u> , MAM '97, pp 51-52, 1998
	2OD	"Electrically reprogrammable FAMOS structure," IBM Technical Disclosure Bulletin, 3/1/73, Vol. 15, Issue 10, pp. 3264-3266
	3OD	Murarka - "Multilevel interconnections for ULSI and GSI era," Materials Science and Engineering, R19 (1997), pp. 87-151
	4OD	Murarka - "Diffusion Barriers - for Thin Film Metallizations," Defect and Diffusion Forum, Vol. 59 (1998), pp. 99-110
	5OD	
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